

# SOT1529-1

LFBGA624, plastic, low profile fine-pitch ball grid array; 624 bumps; 0.8 mm pitch; 21 mm x 21 mm x 1.6 mm body

24 January 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFBGA624
<b>Package type industry code</b>	LFBGA624
<b>Package style descriptive code</b>	LFBGA (low profile fine-pitch ball grid array)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	08-01-2016
<b>Manufacturer package code</b>	98ASA00404D

**Table 1. Package summary**

Parameter	Min	Nom	Max	Unit
package length	-	21	-	mm
package width	-	21	-	mm
seated height	-	1.6	-	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	624	-	



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2 Package outline

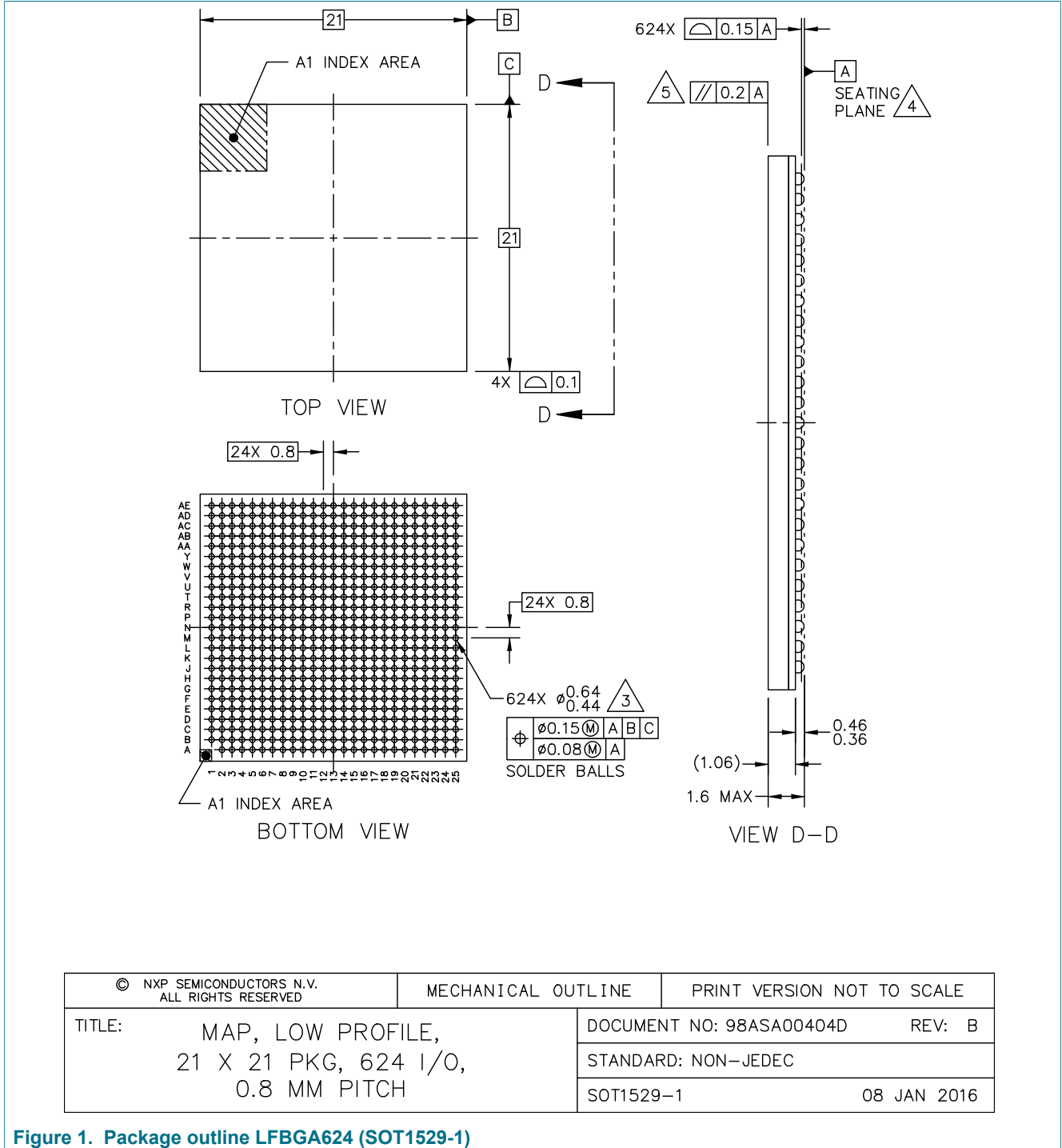


Figure 1. Package outline LFBGA624 (SOT1529-1)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: MAP, LOW PROFILE, 21 X 21 PKG, 624 I/O, 0.8 MM PITCH	DOCUMENT NO: 98ASA00404D	REV: B
	STANDARD: NON-JEDEC	
	SOT1529-1	08 JAN 2016

Figure 2. Package outline note LFBGA624 (SOT1529-1)

### 3 Legal information

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